

RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)

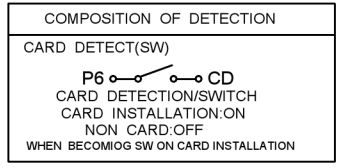
- XKB Connectivity
- PAD AREA
 - KEEP OUT AREA
 - NO COPPER AREA
 - GND PATTERN ONLY

XKB Connectivity

NOTE:

1. 材料 Material:
 - 1-1 外壳 Housing:High Temperature Thermoplastic, (LCP MG350)Color Black U 94V-0
 - 1-2 端子 Contact:Phosphor Bronze(C5210R-SH T=0.12mm)
 - 1-3 外壳 Shell:SUS304-HT=0.10mm
2. 电镀 Plating:
 - 2-1 Contact terminal:
 - Contact area: Gold 2u"Min.Middle Pd-Ni au"min.
 - Solder area: Gold 1u"Min
 - Underplating: Ni overall 80U"Min.
 - 2-2 外壳 Shell:
 - 底镀 Underplating: Ni overall 30U" Min.
 - 焊接区 Solder area: Gold 1u"Min .
3. 规格 Specification:
 - 3-1.接触电流 Contact Current Roting:0.5Amperes.
 - 3-2.介电耐受电压 Dielectric Withstanding Voltage:AC500V r.m.s.
 - 3-3.绝缘电阻 Insulation Resistance:1000 Megohms Minimum At DC 500V.
 - 3-4.接触电阻 Contact Resistance:100 mΩ Maximum.
 - 3-5.寿命 Mating Cyeles:5.000 Cycles.
 - 3-6.工作温度 Operating Temperature:-25℃~+60℃.
4. Product Compliant to RoHs Directive 2002/95/EC and ELV 2000/53/EC
- 5.Recommending A Metal More Than 0.15mm Thick.
Please Confirm Solderadility ,If Use A Metal Mask Less Than 0.15mm Thick.

XKB Connectivity



XKB Connectivity

Pin Define	
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
CD	CARD DETECT
P7	DAT0
P8	DAT1
P9-P12	GND

广东星坤科技股份有限公司

MARK	DESCRIPTION	DATE	REVISED	APPROVED
Δ生				
Δ改				
ΔX				

DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES

DSND	DATE	SCALE: N/A	MODEL TYPE:
DWN	DATE	VIEW:	TF CARD CONN
CHKD	DATE	UNIT: mm/in	PART NO.:
APPD	DATE	SIZE: A4	DWG NO.:
			XKTF-7131-1
XKB INDUSTRIAL PRECISION CO.,LIMITED			WEIGHT
			1.0g
			SHEET
			1/1
			REVISION
			A0